



Material Content Data Sheet



Sales Product Name				IPD122N10N3 G		Issued		19. July 2018	
MA#				MA001213858					
Package				PG-TO252-3-313		Weight*		319.21 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	3.094	0.97	0.97	9692	9692	
leadframe	non noble metal	iron	7439-89-6	0.147	0.05		461		
	inorganic material	phosphorus	7723-14-0	0.044	0.01		138		
	non noble metal	copper	7440-50-8	147.096	46.09	46.15	460815	461414	
wire	non noble metal	aluminium	7429-90-5	4.206	1.32	1.32	13176	13176	
encapsulation	organic material	carbon black	1333-86-4	1.373	0.43		4302		
	plastics	epoxy resin	-	24.034	7.53		75292		
	inorganic material	silicondioxide	60676-86-0	111.929	35.06	43.02	350646	430240	
leadfinish	non noble metal	tin	7440-31-5	3.740	1.17	1.17	11717	11717	
plating	inorganic material	phosphorus	7723-14-0	0.003	0.00		11		
	non noble metal	nickel	7440-02-0	1.421	0.44	0.44	4450	4461	
solder	noble metal	silver	7440-22-4	0.073	0.02		229		
	non noble metal	tin	7440-31-5	0.058	0.02		183		
	non noble metal	lead	7439-92-1	2.787	0.87	0.91	8732	9144	
heatspreader	non noble metal	iron	7439-89-6	0.019	0.01		60		
	inorganic material	phosphorus	7723-14-0	0.006	0.00		18		
	non noble metal	copper	7440-50-8	19.177	6.01	6.02	60078	60156	
*deviation	< 10%			Sum in total:		100.00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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